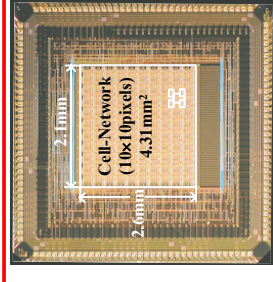
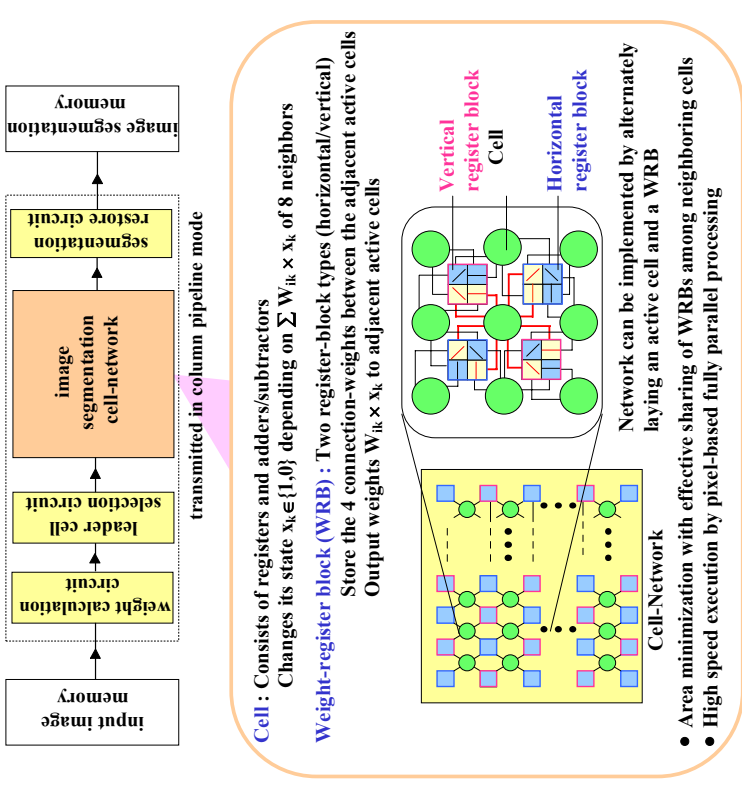
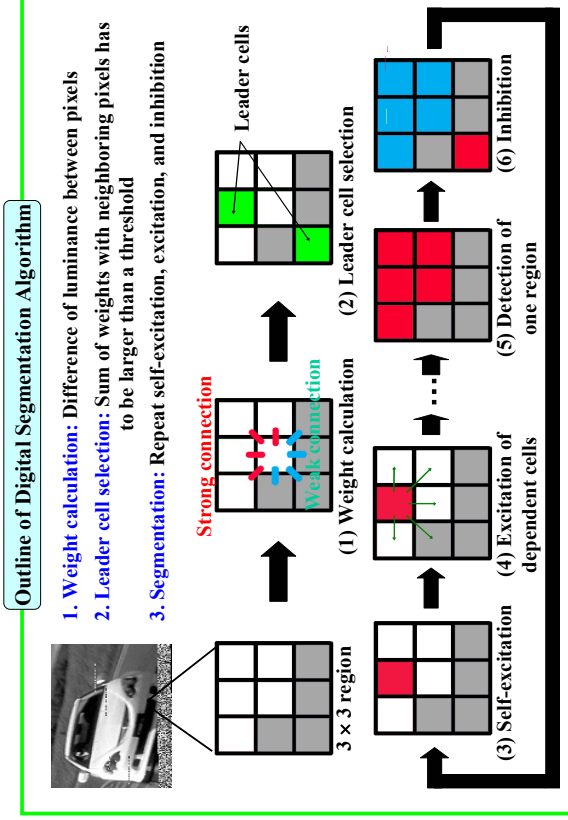
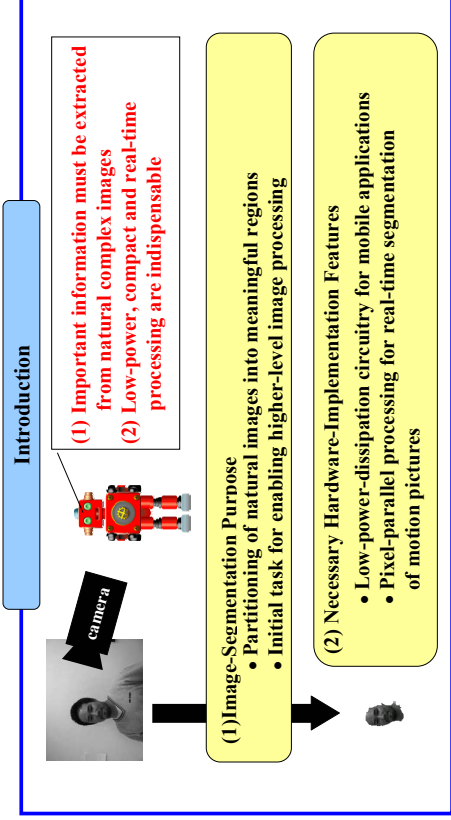




Hiroshima University
Research Center for Nanodevices and Systems (RCNS)
System Design and Architecture Research Division

Low-Power Digital Image Segmentation of Real-Time VGA-Size Motion Pictures

T. Morimoto, Y. Harada, O. Kiriya, H. Adachi, T. Koide, and H. J. Mattausch



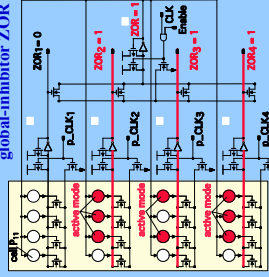
Technology	0.35 μ m 2-Poly 3-Metal CMOS
Measured Max Frequency	25MHz
Power Dissipation (3.3V)	24.4mW@10MHz (ave.)
Segmentation Time Transistors	36.4mW@10MHz (worst)
Pixel Integration Density	9.5psec (worst)
	249,810
	19.6pixel/mm ²

Boundary-Active-Only Scheme (BAO)

- region growing boundary**
- State-transition evaluation is only necessary for the grown boundary cells (Only boundary cells are in active mode and other cells are in stand-by mode)
- More than 75% power reduction is achieved for the 10x10 pixel cell-network
- active mode** ○ stand-by mode ○

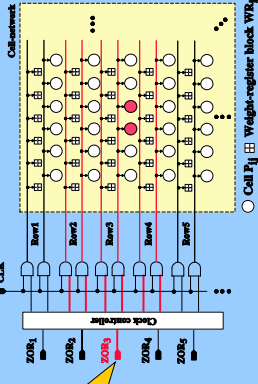
	Without BAO	With BAO	Reduction
Average	24.4mW	5.80mW	76.2%
Worst	30.9mW	6.81mW	78.0%

global-inhibitor ZOR



There are state transitions in row 3. During the next clock-cycle, rows 2, 3, 4 have possibilities that state transition cells exist!

- Calculates an OR function of the active-mode-status signals of all cells
- If there are cells in active mode, this circuit outputs a "1" ($ZOR_i = 1$)
- The region-growing boundary is partly determined by ZOR_i for each row

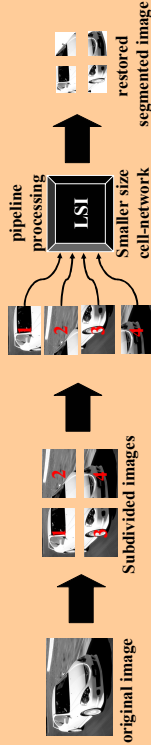


Clock control for each row :

- Only region-growing boundary rows are activated by gated clock signal
- The activated rows are determined from the ZOR_i signals

Subdivided-Image Approach (SIA)

Segmentation time of the proposed segmentation architecture is much faster than required, so sequential processing becomes possible



Chip-size estimation

(Estimated from full-custom layout with 3 metal layers 350nm CMOS technology)

High-Speed Architecture (Weight Parallel, WP)

- 90nm CMOS with 5 routing layers

For 320 x 240 (QVGA) image

Processing Time: < 250μsec at 10MHz

Chip-size: < 116mm² (11mm x 11mm)

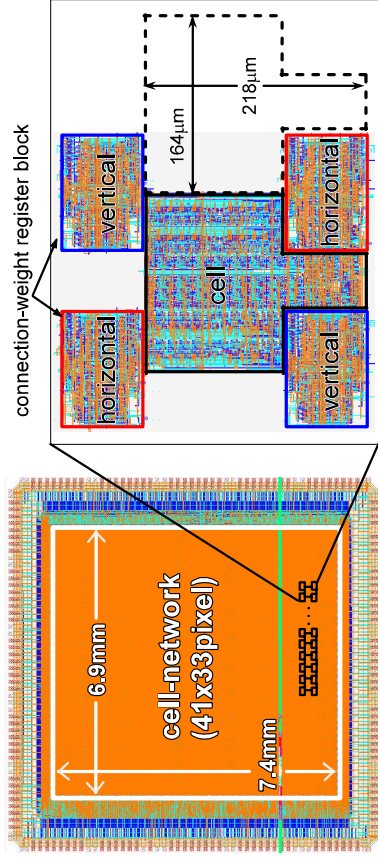
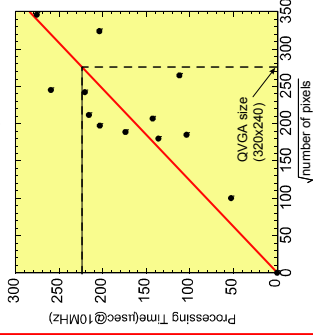
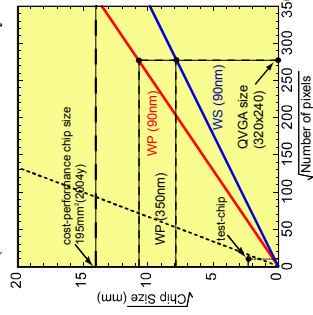
※ Typical chip-size for cost-performance market in 2004 is expected at 195mm² from ITRS2002 Update

High-Density Architecture (Weight Serial, WS)

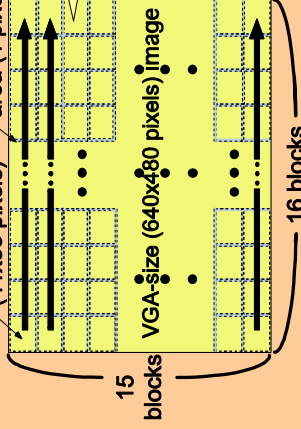
- 90nm CMOS with 5 routing layers

For 320 x 240 (QVGA) image

Chip-size: < 62mm² (8mm x 8mm)



processing block overlapping area (1 pixel)



- pixel block
- Estimated segmentation time : 23μsec
- Estimated power dissipation : 28.0mW

Total processing time : 7.49msec

- Segmentation : (16 x 15) blocks x 23μsec = 5.52msec
- Data in/out : (16 x 15) blocks x 0.1μsec x 82cycles = 1.97msec (at 10MHz clock frequency)